

1.0X0.5mm SMD CHIP LED LAMP (0.2mm Height)

Part Number: APG1005SEC/E-T Hyper-Red

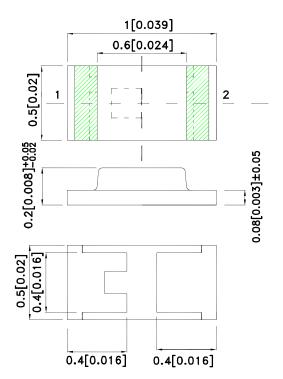
Features

- 1.0mmX0.5mm SMT LED, 0.2mm thickness.
- Low power consumption.
- Wide viewing angle.
- Compatible with automatic placement equipment.
- Ideal for backlight and indicator.
- Package: 4000pcs / reel.
- Moisture sensitivity level : level 3.
- RoHS compliant.

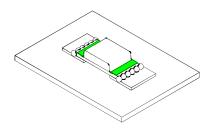
Description

The Hyper-Red source color devices are made with Al-GaInP on GaAs substrate Light Emitting Diode.

Package Dimensions







- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.1 (0.004")$ unless otherwise noted.
- The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.
 The device has a single mounting surface. The device must be mounted according to the specifications.

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Selection Guide

| Part No. | Dice | Lens Type | lv (mcd) [2] @ 20mA | | Viewing Angle [1] |
|----------------|---------------------|-------------|------------------------|------|----------------------|
| | | 2. | Min. | Тур. | 201/2 |
| ADC4005050/F T | Hyper-Red (AlGaInP) | Matan Class | 55 | 127 | - 120° |
| APG1005SEC/E-T | | Water Clear | *20 | *75 | |

Notes:

- 1. 01/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
 2. Luminous intensity/ luminous Flux: +/-15%.

 * Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

Electrical / Optical Characteristics at TA=25°C

| Symbol | Parameter | Device | Тур. | Max. | Units | Test Conditions |
|--------|--------------------------|-----------|------|------|-------|-----------------|
| λpeak | Peak Wavelength | Hyper-Red | 632 | | nm | IF=20mA |
| λD [1] | Dominant Wavelength | Hyper-Red | 624 | | nm | IF=20mA |
| Δλ1/2 | Spectral Line Half-width | Hyper-Red | 20 | | nm | IF=20mA |
| VF [2] | Forward Voltage | Hyper-Red | 2 | 2.4 | V | IF=20mA |
| lR | Reverse Current | Hyper-Red | | 10 | uA | VR=5V |

- 1.Wavelength: +/-1nm.
- 2.Forward Voltage: +/-0.1V.
- 3. Wavelength value is traceable to the CIE127-2007 compliant national standards.

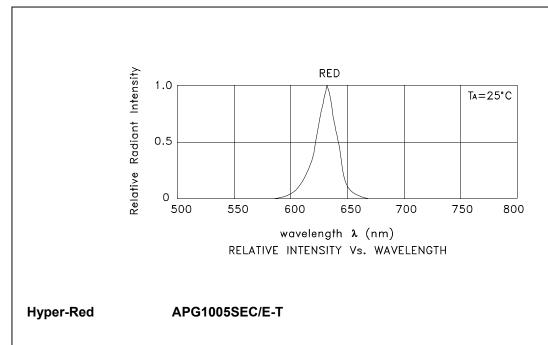
 4. Excess driving current and/or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

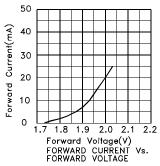
Absolute Maximum Ratings at TA=25°C

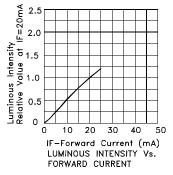
| Absolute maximum rutings at 1A 20 0 | | | | | |
|-------------------------------------|----------------|----|--|--|--|
| Parameter | Hyper-Red | | | | |
| Power dissipation | 60 | mW | | | |
| DC Forward Current | 25 | mA | | | |
| Peak Forward Current [1] | 120 | mA | | | |
| Reverse Voltage | 5 | V | | | |
| Operating Temperature | -40°C To +85°C | | | | |
| Storage Temperature | -40°C To +85°C | | | | |

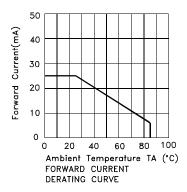
1. 1/10 Duty Cycle, 0.1ms Pulse Width.

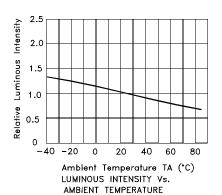
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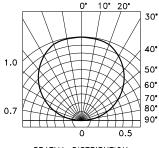






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SPATIAL DISTRIBUTION

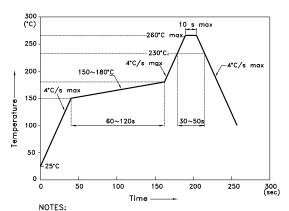
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Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.



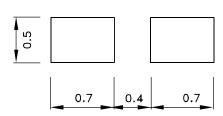
- NOTES:

 1.We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.

 2.Don't cause stress to the epoxy resin while it is exposed to high temperature.

 3.Number of reflow process shall be 2 times or less.

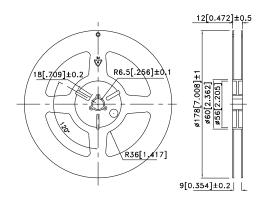
Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)

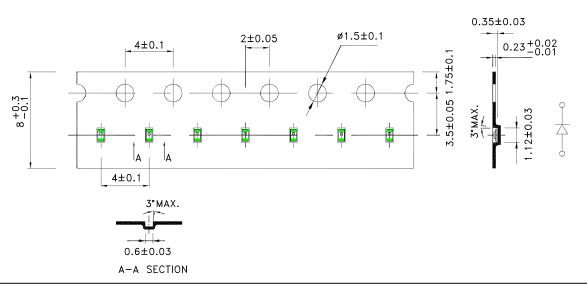


Tape Dimensions

(Units: mm)

Reel Dimension

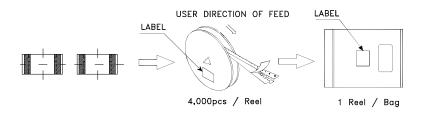


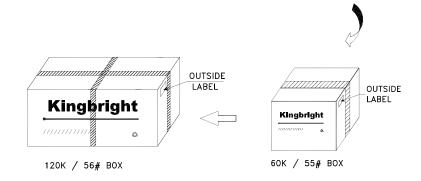


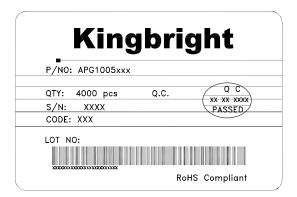
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PACKING & LABEL SPECIFICATIONS

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